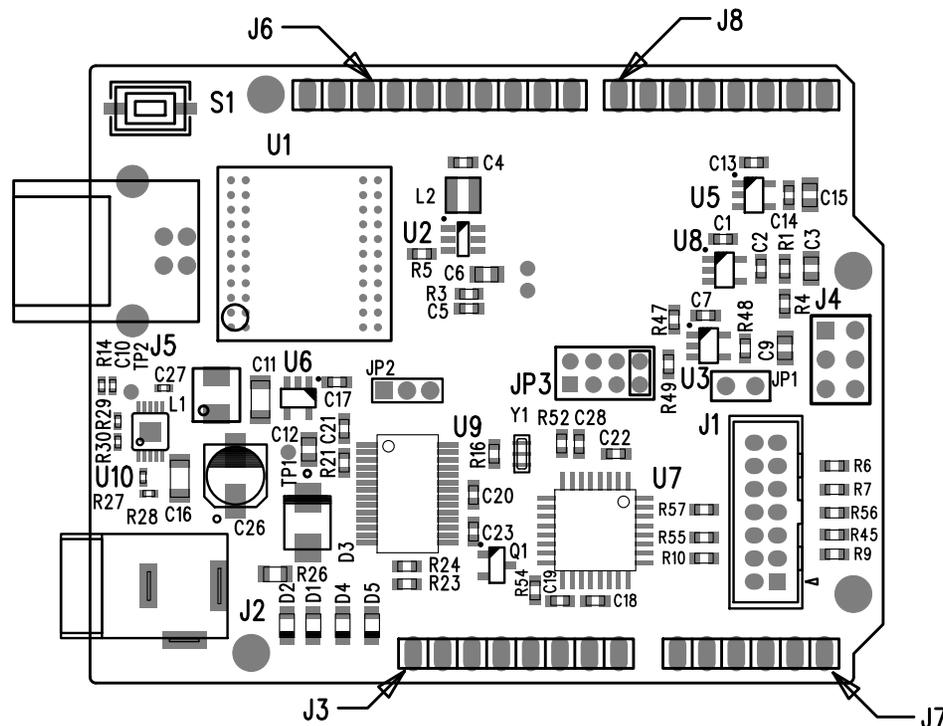


REVISION HISTORY

ECO	REV	DESCRIPTION	APPR	DATE
-	1	PRODUCTION	MARK THOREN	03-25-15



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE REFLOW SOLDER BOTH SIDES. MAXIMUM SOLDER TEMPERATURE SHALL BE <250 DEGREES CELSIUS.
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON ALL BOARD EDGES.
4. DO NOT APPLY ANY ASSEMBLY OR QA STAMPS TO BOARD.
5. J1 THOUGH J8 AND JP3 ARE ALL MOUNTED ON THE TOP SIDE.
6. INSTALL SHUNT IN JP3 AS DEPICTED.
7. INSTALL STICK-ON BUMPONS, MP1-MP4, ON BOTTOM SIDE. (REFER TO SHEET 2, BOTTOM SIDE ASS'Y DRAWING).

APPROVALS

PCB DES.	M. HAWKINS
APP ENG.	MARK THOREN
SCALE = NONE	



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TITLE: ASSEMBLY DRAWING, TOP
LINDUINO ONE:
LINEAR TECHNOLOGY ISOLATED
ARDUINO-COMPATIBLE DEMONSTRATION BOARD

SIZE	IC NO. LTM2884CY	REV.
N/A	DEMO CIRCUIT 2026C	1
FILENAME:	DC2026C-1.PCB	SHT 1 OF 2